MSKSEMI 美森科













ESD

TVS

TSS

MOV

GDT

 PLED

AO3423

Product specification





Features

- -20V,-2.0A, RDS(ON) =95mΩ@VGS =-4.5V
- Improved dv/dt capability
- Fast switching
- Green Device Available

Applications

- Notebook
- Load Switch
- Hand-Held Instruments

BVDSS	RDSON	ID
-20V	95mΩ	-2.0A

Reference News

PACKAGE OUTLINE	PIN Configuration	Marking
SOT-23-3L	G	AS** XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX

Absolute Maximum Ratings Tc=25℃ unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-20	V
V _G S	Gate-Source Voltage	±12	V
Drain Current – Continuous (T _C =25°C)		-2.0	А
l _D	Drain Current – Continuous (T _C =100°C)	-1.6	А
Ірм	Drain Current – Pulsed ¹	-8.0	А
D	Power Dissipation (T _C =25°C)	1.56	W
P _D	Power Dissipation – Derate above 25°C	0.012	W/°C
T _{STG}	Storage Temperature Range	-55 to 150 °C	
TJ	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Unit
R _θ JA	Thermal Resistance Junction to ambient		80	°C/W



Electrical Characteristics (TJ=25 ℃, unless otherwise noted)

Off Characteristics

Symbol	Parameter Conditions		Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =-250uA	-20			V
△BV _{DSS} /△T _J	BV _{DSS} Temperature Coefficient	Reference to 25℃, I _D =-1mA		-0.01		V/°C
	Dunin Course Lookens Courset	V _{DS} =-20V , V _{GS} =0V , T _J =25°C			-1	uA
IDSS	Drain-Source Leakage Current	V _{DS} =-16V , V _{GS} =0V , T _J =125℃			-10	uA
Igss	Gate-Source Leakage Current	V _{GS} =±12V , V _{DS} =0V			±100	nA

On Characteristics

R _{DS(ON)} Static Drain-Source On-Resistance		V _{GS} =-4.5V , I _D =-2.0A		95	120	mΩ
	V _{GS} =-2.5V , I _D =-1A		120	160	11152	
V _{GS(th)}	Gate Threshold Voltage	-V _{GS} =V _{DS} , I _D =-250uA	-0.4	-0.7	-1.1	V
$^{\triangle}V_{\text{GS(th)}}$	V _{GS(th)} Temperature Coefficient	VG5-VD5 , ID230UA		3		mV/°C

Dynamic and switching Characteristics

Dynamic an	d switching Characteristics				
Qg	Total Gate Charge ^{2, 3}			3.0	
Q _{gs}	Gate-Source Charge ^{2,3}	V_{DS} =-10V , V_{GS} =-4.5V , I_{D} =-1A		0.5	 nC
$Q_{ m gd}$	Gate-Drain Charge ^{2, 3}			8.0	
T _{d(on)}	Turn-On Delay Time ^{2 , 3}			10	
Tr	Rise Time ^{2, 3}	V _{DD} =-10V , V _{GS} =-4.5V ,	-	5.5	 nS
T _{d(off)}	Turn-Off Delay Time ^{2,3}	R _G =3Ω I _D =-1A	-	20	 113
Tf	Fall Time ^{2, 3}			6.5	
Ciss	Input Capacitance			180	
Coss	Output Capacitance	V _{DS} =-10V , V _{GS} =0V , F=1MHz		35	 pF
C _{rss}	Reverse Transfer Capacitance			25	

Drain-Source Diode Characteristics and Maximum Ratings

Prairi Courc	2 - Control of the maximum ratings					
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current	V _G =V _D =0V,Force Current			-2.0	Α
I _{SM}	Pulsed Source Current	VG-VD-UV , FOICE Current			-4.0	Α
V _{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =-1A , T _J =25°C			-1.2	V

Note:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 3. Essentially independent of operating temperature.

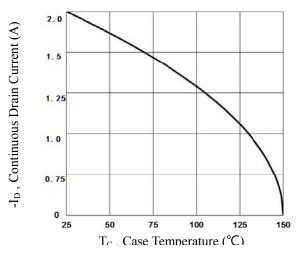


Fig.1 Continuous Drain Current vs. T_c

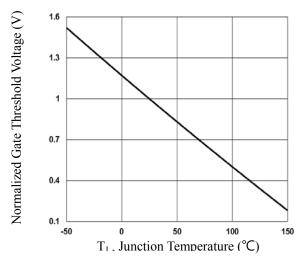


Fig.3 Normalized V_{th} vs. T_J

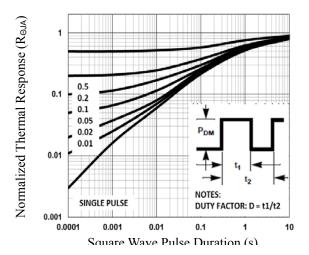


Fig.5 Normalized Transient Impedance

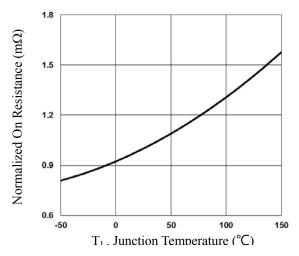


Fig.2 Normalized RDSON vs. T_J

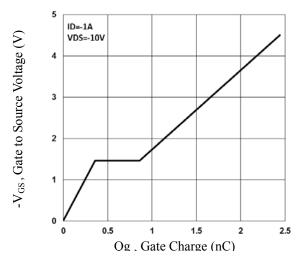


Fig.4 Gate Charge Waveform

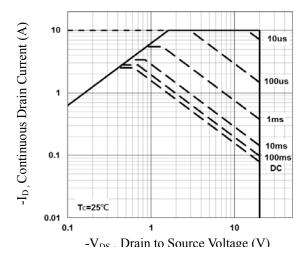
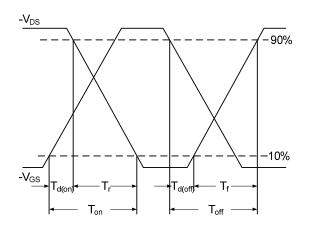
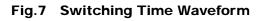


Fig.6 Maximum Safe Operation Area





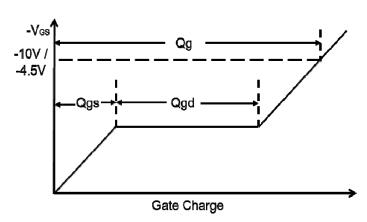
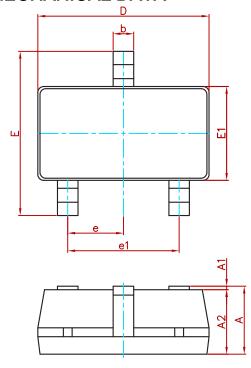
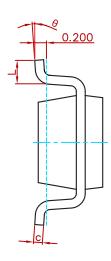


Fig.8 Gate Charge Waveform



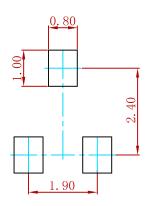
PACKAGE MECHANICAL DATA





Symbol	Dimensions Ir	n Millimeters	Dimension	s In Inches
Syribor	Min.	Max.	Min.	Max.
Α	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
С	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
е	0.950(BSC)		0.037((BSC)
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

Suugested Pad Layout



- 1.Controlling dimension: in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.

REELSPECIFICATION

P/N	PKG	QTY
AO3423	SOT-23-3L	3000



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